TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

PCN20210730004.1B
Qualify additional Assembly site for select SOT devices
Change Notification / Sample Request

Date: August 25, 2021
To: Newark/Farnell PCN

Dear Customer:

Revision B is to correct the devices affected for Group 2 devices.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

PCN Team
SC Business Services

20210730004.1B
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS563200DDCT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20210730004.1B	**PCN Date:**	August 25, 2021

Title:	Qualify additional Assembly site for select SOT devices

Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Nov 02, 2021	**Estimated Sample Availability:**	Provided upon Request

Change Type:

☒ Assembly Site	☐ Design	☐ Wafer Bump Site
☐ Assembly Process	☐ Data Sheet	☐ Wafer Bump Material
☒ Assembly Materials	☐ Part number change	☐ Wafer Bump Process
☐ Mechanical Specification	☐ Test Site	☐ Wafer Fab Site
☒ Packing/Shipping/Labeling	☐ Test Process	☐ Wafer Fab Materials
		☐ Wafer Fab Process

PCN Details

Description of Change:

Revision B is to remove TPS562231DRLR/T from **Group 2** devices. Highlighted and bolded devices are additional devices that was not included on the original PCN notification issued under rev A. The expected first shipment date for the new device will be 90 days from this notice (Nov 20, 2021) for the newly added device only. The proposed 1st ship date of Nov 02, 2021 still applies for the original set of devices.

Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction differences and current assembly sites are as follows:

Group 1 Device:

SOT-5X3 (DRL)	
Assembly Sites	TIPI, HNA, JCETC8, JCETJY, CDAT
Lead Finish	Matte Sn
Mold Compound	4222198 450214 111020003809

Group 2 Device:

SOT-23 (DDC)	
Assembly Sites	TIPI, HNA, UTL, JCETC8, JCETJY, CDAT, TIEM
Lead Finish	Matte Sn
Mold Compound	4222198 450207 8097131 120800005407

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

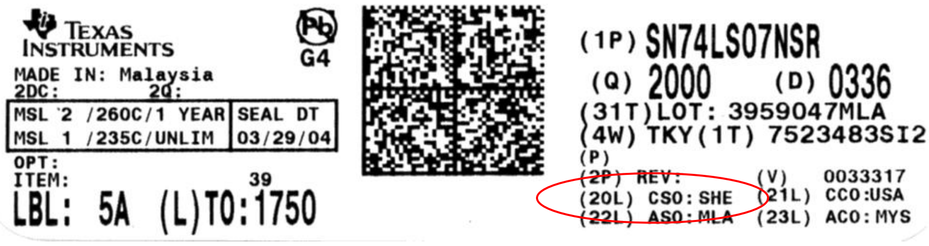
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	**REACH**	**Green Status**	**IEC 62474**
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site		
TI Philippines	Assembly Site Origin (22L)	ASO: PHI
Hana	Assembly Site Origin (22L)	ASO: HNT
UTL	Assembly Site Origin (22L)	ASO: NS2
JCETC8	Assembly Site Origin (22L)	ASO: JC8
JCETJY	Assembly Site Origin (22L)	ASO: JCE
TI Chengdu	Assembly Site Origin (22L)	ASO: CDA
TI Melaka	Assembly Site Origin (22L)	ASO: CU6

Sample product shipping label (not actual product label)



TEXAS INSTRUMENTS
G4
MADE IN: Malaysia
2DC: 2Q:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Group 1 Product Affected:

TPS562231DRLR	**TPS562231DRLT**

Group 2 Product Affected:

SN1501019ADDCR	**SN1708041DDCR**	**TPS54202HDDCT**	TPS563240DDCR
SN1501019DDCR	**SN1708041DDCT**	**TPS561201DDCR**	TPS563240DDCT
SN1501019DDCT	**SN1711021DDCR**	**TPS561201DDCT**	TPS563249DDCR
SN1501020DDCR	**SN1711021DDCT**	**TPS561208DDCR**	TPS563249DDCT
SN1501020DDCT	**SN1711023DDCR**	**TPS561208DDCT**	**TPS56339DDCR**
SN1504025DDCR	**SN1711023DDCT**	**TPS562200DDCR**	**TPS56339DDCT**
SN1504025DDCT	**TPS27081ADDCR**	**TPS562200DDCT**	TPS564201DDCR
SN1504026DDCR	**TPS27082LDDCR**	**TPS562209DDCR**	TPS564201DDCT
SN1504026DDCT	**TPS54200DDCR**	**TPS562209DDCT**	TPS564208DDCR
SN1611045DDCR	**TPS54200DDCT**	~~**TPS562231DRLR**~~	TPS564208DDCT
SN1702049DDCR	**TPS54201DDCR**	~~**TPS562231DRLT**~~	**TPS92200D1DDCR**
SN1704026DDCR	**TPS54201DDCT**	**TPS563200DDCR**	**TPS92200D2DDCR**
SN1704026DDCT	**TPS54202DDCR**	**TPS563200DDCT**	
SN1706011DDCR	**TPS54202DDCT**	**TPS563209DDCR**	
SN1706011DDCT	**TPS54202HDDCR**	**TPS563209DDCT**	

Group 1 Qualification Report
(SOT-5X3)

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	TIPI TLV62568DRL	CDAT TPS562231DRL
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C	1000 hours	-	-
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 hours	-	3/231/0
AC	Autoclave 121C	96 hours	3/231/0	-
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	JCETC8 TLV62568PDRL	HNA TMP390A2DRL	JCETJY TMP302BDRL
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	-	3/231/0
HTSL	Biased HAST 110C/85%RH	264 hours	-	3/231/0	-
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0	3/231/0 (b)
UHAST	Unbiased HAST, 130C/85%RH	96 hours	-	3/231/0	3/231/0
AC	Autoclave 121C	96 hours	3/231/0	-	-
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0 (a)	3/66/0 (b)
MQ	Manufacturability	-	Pass	Pass	Pass

All qualification devices in the tables are qualified at L1-260C MSL rating.

Note a – Data collected on SN74AVC1T45DRL
Note b – Data collected on TMP102AIDRL and TMP302BDRL

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable
- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

Group 2 Qualification Report
(SOT-23)

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	TIPI TPS563249DDC	CDAT TPS563249DDC
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C	1000 hours	-	-
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 hours	3/231/0	3/231/0
AC	Autoclave 121C	96 hours	-	-
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (TPS563201DDC)	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	JCETC8 TPS563208DDC	JCETJY TLV62569PDDC
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C	1000 hours	-	-
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 hours	3/231/0	-
AC	Autoclave 121C	96 hours	-	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0 (TPS27081ADDC)
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	UTL LM73CxQDDCRQ1	TIEM TPL5010QDDCRQ1	HNA LV2862XLVDDC
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C	1000 hours	-	3/231/0	-
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0 (a)	-	3/135/0 (b)
UHAST	Unbiased HAST, 130C/85%RH	96 hours	-	3/231/0	-
AC	Autoclave 121C	96 hours	3/231/0	-	3/231/0
SD	Solderability	8 Hour Steam	2/44/0 (TPS62242QDDC)	2/44/0 (LM2734XQMK)	3/66/0 (b)

	Stress Test	Duration	UTL LM73CxQDDCRQ1	TIEM TPL5010QDDCRQ1	HNA LV2862XLVDDC
		age or 155C Dry Bake			
MQ	Manufacturability	-	Pass	Pass	Pass

All qualification devices in the tables are qualified at L1-260C MSL rating.

Note a – Data collected on TPS3702EX33QDDCRQ1 and LM73CxQDDCRQ1
Note b – Data collected on LMP8640QMKX-T/NOPB

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable
- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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Asia Pacific	PCNAsiaContact@list.ti.com
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